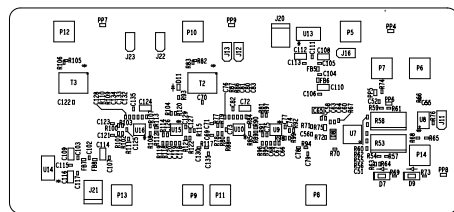


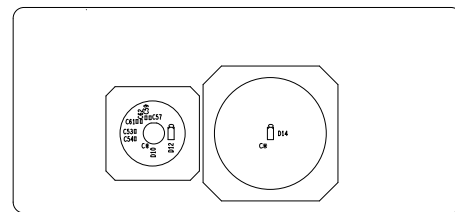
THIS DRAWING IS INTENDED TO HELP IN THE ASSEMBLY OF THE DESIGN.

REVISIONS			
ZONE	LTR	DESCRIPTION	DATE

1. REFER TO ODB++ FILE FOR SPECIFIC COMPONENT LOCATION INFORMATION.
2. USE WATER SOLUBLE FLUX DURING BOARD ASSEMBLY. ASSEMBLY MUST BE RoHS COMPLIANT AND LEAD FREE.
3. IPC-A-610 / ACCEPTABILITY OF ELECTRONIC ASSEMBLIES, CLASS2, CURRENT REVISION.



TOP VIEW



BOTTOM VIEW

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES +/- .XX +/- .01 +/- .XXX +/- .005 +/-	CONTRACT NO.		TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	ASSEMBLY DRAWING TIDA-01187	
DRAWN JV SMITH	08-18-16	REV. A		
MATERIAL	ENGR D GUIDRY	08-18-16	SIZE B	CODE IDENT NO.
SEE NOTE 5			DRAWING NO.	
FINISH	SEE NOTES 7, 8, 9		SCALE NONE	SHEET 1 OF 1
DO NOT SCALE DRAWING				

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